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COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	GOLD OVER NICKEL
Center contact	BERYLLIUM COPPER	GOLD OVER NICKEL
Outer contact	-	-
Insulator	PEEK	
Gasket	-	
Others parts	-	-
-	-	-
_	_	-



Technical Data Sheet

ENVIRONMENTAL

OTHER CHARACTERISTICS

STRAIGHT JACK RECEPTACLE FOR PCB SMT TYPE - REEL OF 100

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PACKAGING

Γ	100	Contact us	Contact us	
Γ	Standard	Unit	Other	

ELECTRICAL CHARACTERISTICS

Impedance 75 Frequency 0-6 GHz

x F(GHz) Maxi √F(GHz) dB Maxi VSWR 1,25 0.0000 Insertion loss 0.1 RF leakage NA - F(GHz)) dB Maxi - (Voltage rating 335 Veff Maxi

Dielectric withstanding voltage 1000 Veff mini Operating temperature Insulation resistance 1000 $M\Omega$ mini

-55/+155 °C Hermetic seal NA Atm.cm3/s Panel leakage NA

MECHANICAL CHARACTERISTICS

SPECIFICATION Center contact retention

10 Axial force - Mating End N mini Axial force - Opposite end 10 N mini NA N.cm mini Torque

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight 0.5300 g

Others:

Assembly instruction:

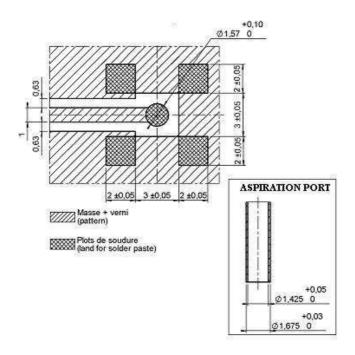




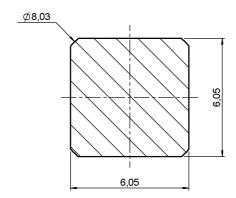
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MCX SERIES - INFORMATION

Coplanar line : pattern and signal are on the same side . Thickness of PCB :.064(1.6mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed exept for the land pattern on the PCB .



SHADOW OF MCX RECEPTACLE FOR VIDEO CAMERA







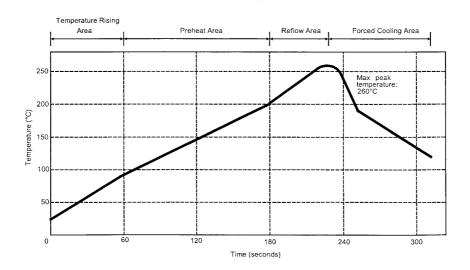
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SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (5.9 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow.

 Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec





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